RENESAS

HMU16, HMU17 16 x 16-Bit CMOS Parallel Multipliers

DATASHEET

FN2803 Rev 4.00 November 1999

The HMU16 and HMU17 are high speed, low power CMOS 16-bit x 16-bit multipliers ideal for fast, real time digital signal processing applications.

The X and Y operands along with their mode controls (TCX and TCY) have 17-bit input registers. The mode controls independently specify the operands as either two's complement or unsigned magnitude format, thereby allowing mixed mode multiplication operations.

Two 16-bit output registers are provided to hold the most and least significant halves of the result (MSP and LSP). For asynchronous output, these registers may be made transparent through the use of the Feedthrough Control (FT).

Additional inputs are provided for format adjustment and rounding. The Format Adjust control (FA) allows the user to select either a left shifted 31-bit product or a full 32-bit product, whereas the round control (RND) provides the capability of rounding the most significant portion of the result.

The HMU16 has independent clocks (CLKX, CLKY, CLKL, CLKM) associated with each of these registers to maximize throughput and simplify bus interfacing. The HMU17 has only a single clock input (CLK), but makes use of three register enables (ENX, ENY and ENP). The ENX and ENY inputs control the X and Y Input Registers, while ENP controls both the MSP and LSP Output Registers. This configuration facilitates the use of the HMU17 for microprogrammed systems.

The two halves of the product may be routed to a single 16-bit three-state output port via a multiplexer, and in addition, the LSP is connected to the Y-input port through a separate three-state buffer.

Features

- 16 x 16-Bit Parallel Multiplier with Full 32-Bit Product
- High-Speed (35ns) Clocked Multiply Time
- Low Power Operation
 - I_{CCSB} = 500µA Maximum
 - I_{CCOP} = 7.0mA Maximum at 1MHz
- Supports Two's Complement, Unsigned Magnitude and Mixed Mode Multiplication
- HMU16 is Compatible with the AM29516, LMU16, IDT7216 and the CY7C516
- HMU17 is Compatible with the AM29517, LMU17, IDT7217 and the CY7C517
- TTL Compatible Inputs/Outputs
- Three-State Outputs

Applications

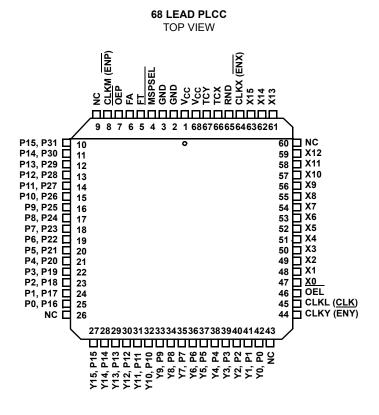
- Fast Fourier Transform Analysis
- Digital Filtering
- Graphic Display Systems
- Image Processing
- Radar and Sonar
- · Speech Synthesis and Recognition

Ordering Information

PART NUMBER	TEMP. RANGE (^O C)	PACKAGE	PKG. NO.
HMU16JC-35	0 to 70	68 Ld PLCC	N68.95
HMU16JC-45	0 to 70	68 Ld PLCC	N68.95
HMU16GC-35	0 to 70	68 Ld CPGA	G68.B
HMU16GC-45	0 to 70	68 Ld CPGA	G68.B
HMU17JC-35	0 to 70	68 Ld PLCC	N68.95
HMU17JC-45	0 to 70	68 Ld PLCC	N68.95
HMU17GC-35	0 to 70	68 Ld CPGA	G68.B
HMU17GC-45	0 to 70	68 Ld CPGA	G68.B



Pinouts



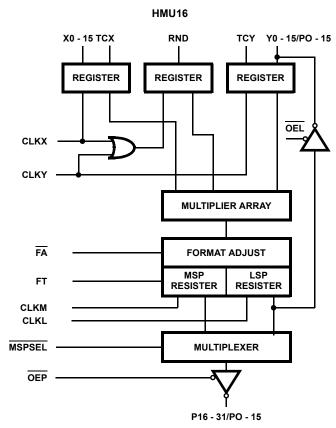
68	LEAD	CPGA
	TOP V	IEW

11		N/C	X13	X15	RND	тсү	v _{cc}	GND	FT	OEP	
10	X11	X12	X14	C <u>LKX</u> (ENX)	тсх	v _{cc}	GND	<u>MSP</u> SEL	FA	C <u>LKM</u> (ENP)	N/C
9	Х9	X10								P30/ P14	P31/ P15
8	Х7	X8								P28/ P12	P29/ P13
7	X5	X6								P26/ P10	P27/ P11
6	Х3	X4								P24/ P8	P25/ P9
5	X1	X2								P22/ P6	P23/ P7
4	OEL	X0								P20/ P4	P21/ P5
3	C <u>LKY</u> (ENY)	CLKL (CLK)								P18/ P2	P19/ P3
2	N/C	Y0/P0	Y2/P2	Y4/P4	Y6/P6	Y8/P8	Y10/ P10	Y12/ P12	Y14/ P14	P16/ P0	P17/ P1
1		Y1/P1	Y3/P3	Y5/P5	Y7/P7	Y9/P9	Y11/ P11	Y13/ P13	Y15/ P15	N/C	
	Α	в	С	D	Е	F	G	н	J	к	L

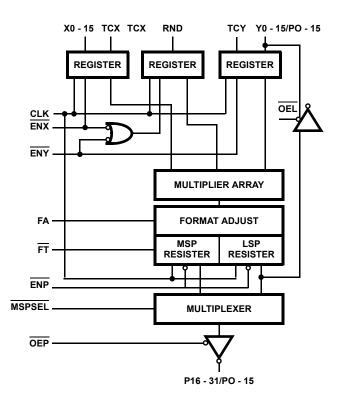
FN2803 Rev 4.00 November 1999



Functional Block Diagrams







FN2803 Rev 4.00 November 1999



Pin Description

SYMBOL	PLCC PIN NUMBER	TYPE	DESCRIPTION
V _{CC}	1, 68		$V_{CC}.$ The +5V power supply pins. A 0.1 μF capacitor between the V_{CC} and GND pins is recommended.
GND	2, 3		GND. The device ground.
X0-X15	47-59, 61-63	I	X-Input Data. These 16 data inputs provide the multiplicand which may be in two's complement or unsigned magnitude format.
Y0-Y15/ P0-P15	27-42	I/O	Y-Input/LSP Output Data. This 16-bit port is used to provide the multiplier which may be in two's complement or unsigned magnitude format. It may also be used for output of the Least Significant Product (LSP).
P16-P31/ P0-P15	10-25	0	Output Data. This 16-bit port may provide either the MSP (P16-31) or the LSP (P0-15).
TCY, TCX	66, 67	I	Two's Complement Control. Input data is interpreted as two's complement when this control is HIGH. A LOW indicates the data is to be interpreted as unsigned magnitude format.
FT	5	I	Feed through Control. When this control is HIGH, both the MSP and LSP Registers are transparent. When LOW, the registers are latched by their associated clock signals.
FA	6	I	Format Adjust Control. A full 32-bit product is selected when this control line is HIGH. A LOW on this control line selects a left shifted 31-bit product with the sign bit replicated in the LSP. This control is normally HIGH, except for certain two's complement integer and fractional applications.
RND	65	I	Round Control. When this control is HIGH, a one is added to the Most Significant Bit (MSB) of the LSP. This position is dependent on the FA control; \overline{FA} = HIGH indicates RND adds to the 2-15 bit (P15), and \overline{FA} = LOW indicates RND adds to the 2 ⁻¹⁶ bit (P14).
MSPSEL	4	I	Output Multiplexer Control. When this control is LOW, the MSP is available for output at the dedicated output port, and the LSP is available at the Y-input/LSP output port. When MSPSEL is HIGH, the LSP is available at both ports and the MSP is not available for output.
OEL	46	I	Y-In/P0-15 Output Port Three-State Control. When OEL is HIGH, the output drivers are in the high impedance state. This state is required for Ydata input. When OEL is LOW, the port is enabled for LSP output.
OEP	7	I	P16-31/P0-15 Output Port Three-State Control. A LOW on this control line enables the output port. When $\overrightarrow{\text{OEP}}$ is HIGH, the output drivers are in the high impedance state.
THE FOLLOWI	NG PIN DESCRIP		LY TO THE HMU16 ONLY
CLKX	64	I	X-Register Clock. The rising edge of this clock loads the X-data Input Register along with the TCX and RND Registers.
CLKY	44	I	Y-Register Clock. The rising edge of this clock loads the Y-data Input Register along with the TCY and RND Registers.
CLKM	8	I	MSP Register Clock. The rising edge of CLKM loads the Most Significant Product (MSP) Register
CLKL	45	I	LSP Register Clock. The rising edge of CLKL loads the Least Significant Product (LSP) Register
	NG PIN DESCRIP		LY TO THE HMU17 ONLY
CLK	45	I	Clock. The rising edge of this clock will load all enabled registers.
ENX	64	I	X-Register Enable. When $\overline{\text{ENX}}$ is LOW, the X-register is enabled; X-input data and TCX will be latched at the rising edge of CLK. When $\overline{\text{ENX}}$ is high, the X-register is in a hold mode.
ENY	44	I	Y-Register Enable. ENY enables the Y-register. (See ENX).
ENP	8	I	Product Register Enable. ENP enables the Product Register. Both the MSP and LSP Sections are enabled by ENP. (See ENX).

Functional Description

The HMU16/HMU17 are high speed 16 x 16-bit multipliers designed to perform very fast multiplication of two 16-bit binary numbers. The two 16-bit operands (X and Y) may be independently specified as either two's complement or unsigned magnitude format by the two's complement controls (TCX and TCY). When either of these control lines is LOW, the respective operand is treated as an unsigned 16-bit value; and when it is HIGH, the operand is treated as a signed value represented in two's complement format. The operands along with their respective controls are latched at the rising edge of the associated clock signal. The HMU16 accomplishes this through the use of independent clock inputs for each of the Input Registers (CLKX and CLKY), while the HMU17 utilizes a single clock signal (CLK) along with the X and Y register enable inputs (ENX and ENY).

Input controls are also provided for rounding and format adjustment of the 32-bit product. The Round input (RND) is provided to accommodate rounding of the most significant portion of the product by adding one to the Most Significant Bit (MSB) of the LSP Register. The position of the MSB is dependent on the state of the Format Adjust Control (see Pin Descriptions and Multiplier Input/Output Format Tables). The Round input is latched into the RND Register whenever either of the input registers is clocked. The Format Adjust control (FA) allows the product output to be formatted. When the \overline{FA} control is HIGH, a full 32-bit product is output; and when FA is LOW, a left-shifted 31-bit product is output with the sign bit replicated in bit position 15 of the LSP. The FA control must be HIGH for unsigned magnitude, and mixed mode multiplication operations. It may be LOW for certain two's complement integer and fractional operations only (see Multiplier Input/ Output Formats Table).

The HMU16/HMU17 multipliers are equipped with two 16-bit Output Registers (MSP and LSP) which are provided to hold the most and least significant portions of the resultant product respectively. The HMU16 uses independent clocks (CLKM and CLKL) for latching the two output registers, while the HMU17 uses a single clock input (CLK) along with the Product Latch Enable (ENP). The MSP and LSP Registers may also be made transparent for asynchronous output through the use of the Feed through Control (FT). There are two output configurations which may be selected when using the HMU16/HMU17 multipliers. The first configuration allows the simultaneous access of the most and least significant halves of the product. When the MSPSEL input is LOW, the Most Significant Product will be available at the dedicated output port (P16-31/P0-15). The Least Significant Product is simultaneously available at the bidirectional port shared with the Y-inputs (Y0-15/P0-15) through the use of the LSP output enable (OEL). The other output configuration involves multiplexing the MSP and LSP Registers onto the dedicated output port through the use of the MSPSEL control. When the MSPSEL control is LOW, the Most Significant Product will be available at the dedicated output port; and when MSPSEL is HIGH, the Least Significant Product will be available at this port. This configuration allows access of the entire 32-bit product by a 16-bit wide system bus.



Multiplier Input/Output Formats

BINARY POINT

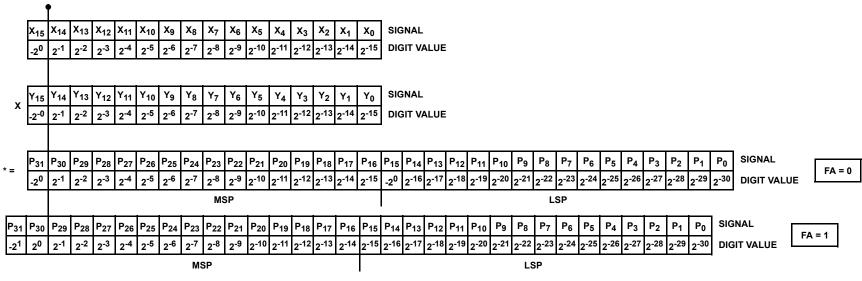


FIGURE 1. FRACTIONAL TWO'S COMPLEMENT NOTATION

NOTE: In this format an overflow occurs in the attempted multiplication of the two's complement number 1,000 . . . 0 with 1,000 . . . 0 yielding an erroneous product of -1 in the fraction case and -2³⁰ in the integer case.

BINARY POINT

=

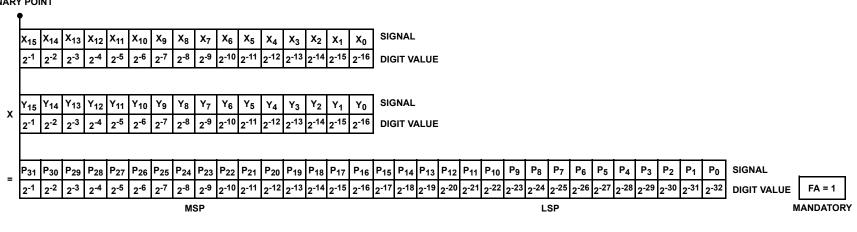
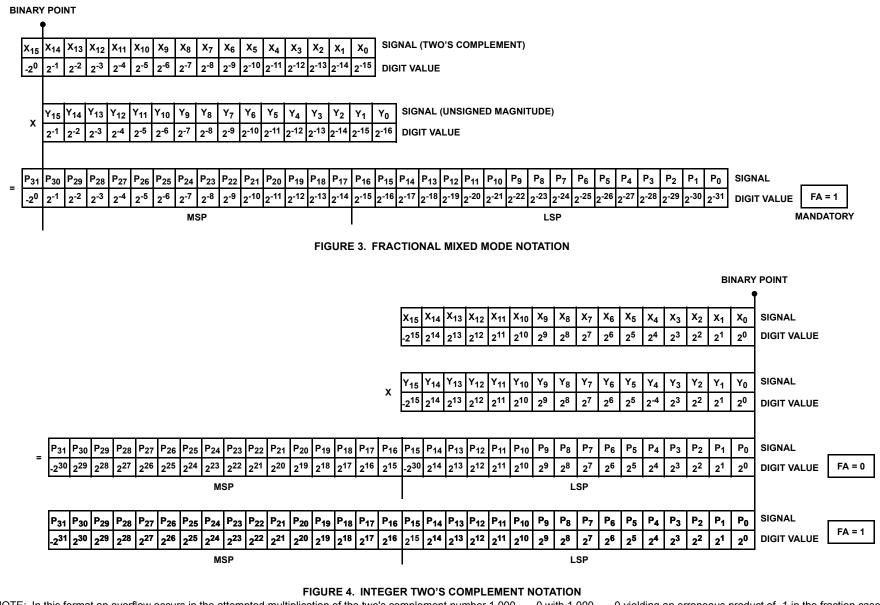


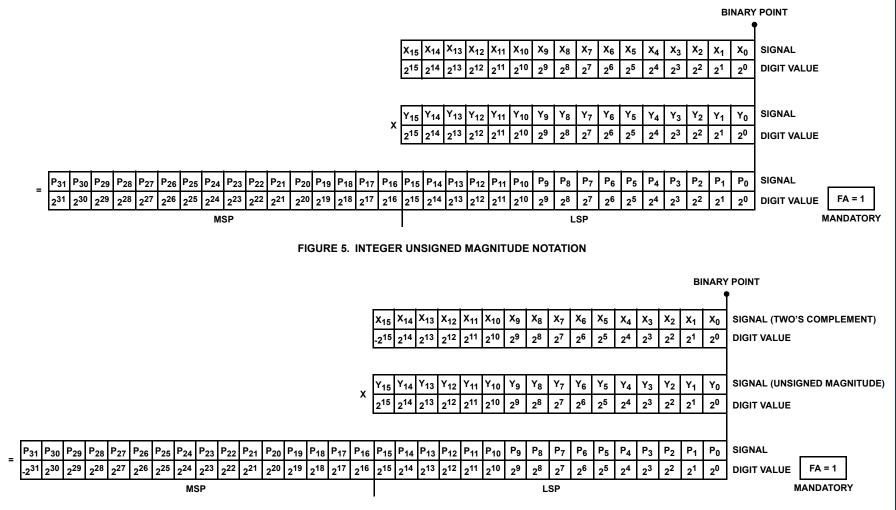
FIGURE 2. FRACTIONAL UNSIGNED MAGNITUDE NOTATION

Multiplier Input/Output Formats (Continued)



NOTE: In this format an overflow occurs in the attempted multiplication of the two's complement number 1,000 ... 0 with 1,000 ... 0 yielding an erroneous product of -1 in the fraction case and -2³⁰ in the integer case.

Multiplier Input/Output Formats (Continued)



HMU16, HMU17

FIGURE 6. INTEGER MIXED MODE NOTATION

Absolute Maximum Ratings

Supply Voltage +8.0V
Input, Output or I/O Voltage Applied GND 0.5V to V _{CC} +0.5V
Storage Temperature Range

Operating Conditions

Voltage Range	. +4.75V to +5.25V
Temperature Range	0 ^o C to 70 ^o C

Thermal Information

Thermal Resistance (Typical, Note 1)	θ _{JA} (^o C/W)	θ _{JC} (^o C/W)
PLCC	43.2	15.1
CPGA	42.69	10.0
Maximum Package Power Dissipation at 7	'0°C	
PLCC		1.7W
CPGA		2.46
Maximum Junction Temperature		
PLCC		150 ⁰ C
CPGA		175 ⁰ C
Maximum Lead Temperature (Soldering, 1	0s)	300 ⁰ C

Die Characteristics

CAUTION: Stresses above those listed in the ``Absolute Maximum Ratings'' may cause permanent damage to the device. This is a stress only rating, and operation at these or any other conditions above those indicated in the operations sections of this specification is not implied.

NOTE:

1. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

DC Electrical Specifications V_{CC} = 5.0V ±5%, T_A = 0°C to 70°C

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
Logical One Input Voltage	V _{IH}	V _{CC} = 5.25V	2.0	-	V
Logical Zero Input Voltage	VIL	V _{CC} = 4.75V	-	0.8	V
Output High Voltage	V _{OH}	I _{OH} = 400mA, V _{CC} = 4.75V	2.6	-	V
Output Low Voltage	V _{OL}	I _{OL} = +4.0mA, V _{CC} = 4.75V	-	0.4	V
Input Leakage Current	l	$V_{I} = V_{CC}$ or GND, $V_{CC} = 5.25V$	10	10	μA
Output or I/O Leakage Current	Ι _Ο	$V_{O} = V_{CC}$ or GND, $V_{CC} = 5.25V$	10	10	μA
Standby Power Supply Current	ICCSB	$V_{I} = V_{CC}$ or GND, $V_{CC} = 5.25V$ Outputs Open	-	500	μΑ
Operating Power Supply Current	ICCOP	$V_I = V_{CC}$ or GND, $V_{CC} = 5.25V$ f = 1MHz (Note 2)	-	7.0	mA

NOTE:

2. Operating Supply Current is proportional to frequency, Typical rating is 5mA/MHz.

Capacitance T_A = 25^oC, Note 3

PARAMETER	SYMBOL	TEST CONDITIONS	TYPICAL	UNITS
Input Capacitance	C _{IN}	Frequency = 1MHz. All measurements	15	pF
Output Capacitance	C _{OUT}	referenced to device ground.	10	pF
I/O Capacitance	C _{I/O}		10	pF

NOTE:

3. Not tested, but characterized at initial design and at major process/design changes.

		TEST	HMU16/H	IMU17-35	HMU16/H	IMU17-45	
PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	MIN	MAX	UNITS
Unclocked Multiply Time	t _{MUC}		-	55	-	70	ns
Clocked Multiply Time	t _{MC}		-	35	-	45	ns
X, Y, RND Setup Time	t _S		15	-	18	-	ns
X, Y, RND Hold Time	t _H		2	-	2	-	ns
Clock Pulse Width High	t _{PWH}		10	-	15	-	ns
Clock Pulse Width Low	t _{PWL}		10	-	15	-	ns
MSPSEL to Product Out	t _{PDSEL}		-	22	-	25	ns
Output Clock to P	tPDP		-	22	-	25	ns
Output Clock to Y	t _{PDY}		-	22	-	25	ns
Three-State Enable Time	t _{ENA}	Note 4	-	22	-	25	ns
Three-State Disable Time	t _{DIS}		-	22	-	25	ns
Clock Enable Setup Time (HMU17 Only)	t _{SE}		15	-	15	-	ns
Clock Enable Hold Time (HMU17 Only)	t _{HE}		2	-	2	-	ns
Clock Low Hold Time CLKXY Relative to CLKML (HMU16 Only)	tHCL	Note 5	0	-	0	-	ns
Output Rise Time	t _r	From 0.8V to 2.0V	-	8	-	8	ns
Output Fall Time	t _f	From 2.0V to 0.8V	-	8	-	8	ns

AC Electrical Specifications $V_{CC} = 5.0V \pm 5\%$, T_A = 0°C to 70°C, Note 6

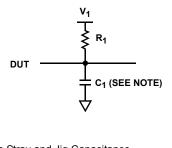
NOTES:

4. Transition is measured at \pm 200mV from steady state voltage with loading specified in AC Test Circuit, V₁ = 1.5V, R₁ = 500 Ω and C₁ = 40pF.

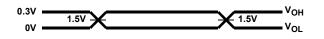
5. To ensure the correct product is entered in the output registers, new data may not be entered into the input registers before the output registers have been clocked.

6. Refer to AC Test Circuit, with V₁ = 2.4V, R₁ = 500Ω and C₁ = 40pF.

AC Test Circuit



AC Testing Input, Output Waveforms



NOTE: AC Testing: All parameters tested as per test circuit. Input rise and fall times are driven at 1ns/V.



Timing Diagrams

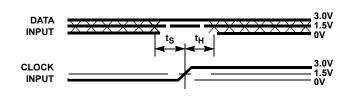


FIGURE 7. SETUP AND HOLD TIME

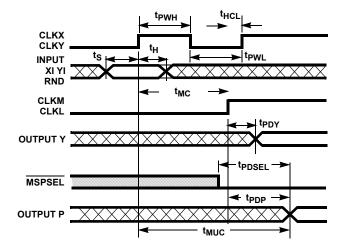


FIGURE 9. HMU16 TIMING DIAGRAM

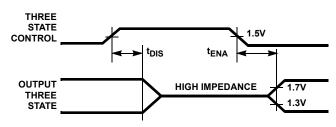


FIGURE 8. THREE-STATE CONTROL

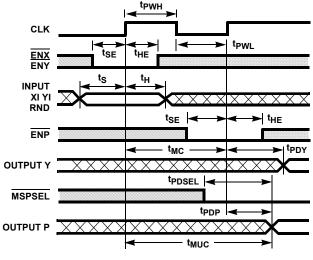
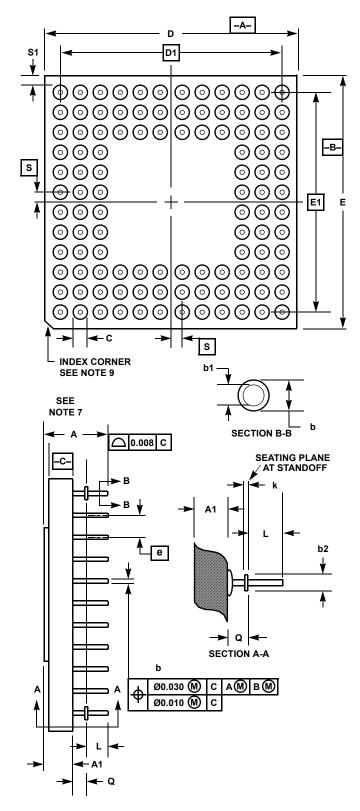


FIGURE 10. HMU17 TIMING DIAGRAM



Ceramic Pin Grid Array Packages (CPGA)



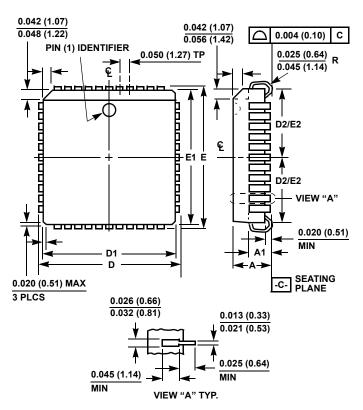
G68.B MIL-STD-1835 CMGA3-P68D (P-AC) 68 LEAD CERAMIC PIN GRID ARRAY PACKAGE

	INC	HES	MILLIN	IETERS		
SYMBOL	MIN	MAX	MIN	MAX	NOTES	
А	0.215	0.345	5.46	8.76	-	
A1	0.070	0.145	1.78	3.68	3	
b	0.016	0.0215	0.41	0.55	8	
b1	0.016	0.020	0.41	0.51	-	
b2	0.042	0.058	1.07	1.47	4	
С	-	0.080	-	2.03	-	
D	1.140	1.180	28.96	29.97	-	
D1	1.000	BSC	25.4 BSC		-	
Е	1.140	1.180	28.96	29.97	-	
E1	1.000	BSC	25.4 BSC		-	
е	0.100	BSC	2.54 BSC		6	
k	0.008	B REF	0.20 REF		-	
L	0.120	0.140	3.05	3.56	-	
Q1	0.025	0.060	0.64	1.52	5	
S	0.000	BSC	0.00 BSC		10	
S1	0.003	-	0.08	-	-	
М	11		-	11	1	
Ν	-	121	-	121	2	
Rev. 0 6/20/9						

NOTES:

- 1. "M" represents the maximum pin matrix size.
- 2. "N" represents the maximum allowable number of pins. Number of pins and location of pins within the matrix is shown on the pinout listing in this data sheet.
- Dimension "A1" includes the package body and Lid for both cavity-up and cavity-down configurations. This package is cavity down. Dimension "A1" does not include heatsinks or other attached features.
- Standoffs are required and shall be located on the pin matrix diagonals. The seating plane is defined by the standoffs at dimension "Q1".
- 5. Dimension "Q1" applies to cavity-down configurations only.
- 6. All pins shall be on the 0.100 inch grid.
- 7. Datum C is the plane of pin to package interface for both cavity up and down configurations.
- 8. Pin diameter includes solder dip or custom finishes. Pin tips shall have a radius or chamfer.
- 9. Corner shape (chamfer, notch, radius, etc.) may vary from that shown on the drawing. The index corner shall be clearly unique.
- 10. Dimension "S" is measured with respect to datums A and B.
- 11. Dimensioning and tolerancing per ANSI Y14.5M-1982.
- 12. Controlling dimension: INCH.

Plastic Leaded Chip Carrier Packages (PLCC)



N68.95 (JEDEC MS-018AE ISSUE A) 68 LEAD PLASTIC LEADED CHIP CARRIER PACKAGE

	INCHES		MILLIMETERS		
SYMBOL	MIN	MAX	MIN	MAX	NOTES
А	0.165	0.180	4.20	4.57	-
A1	0.090	0.120	2.29	3.04	-
D	0.985	0.995	25.02	25.27	-
D1	0.950	0.958	24.13	24.33	3
D2	0.441	0.469	11.21	11.91	4, 5
Е	0.985	0.995	25.02	25.27	-
E1	0.950	0.958	24.13	24.33	3
E2	0.441	0.469	11.21	11.91	4, 5
Ν	68		68		6

Rev. 2 11/97

NOTES:

- 1. Controlling dimension: INCH. Converted millimeter dimensions are not necessarily exact.
- 2. Dimensions and tolerancing per ANSI Y14.5M-1982.
- 3. Dimensions D1 and E1 do not include mold protrusions. Allowable mold protrusion is 0.010 inch (0.25mm) per side. Dimensions D1 and E1 include mold mismatch and are measured at the extreme material condition at the body parting line.
- 4. To be measured at seating plane -C- contact point.
- 5. Centerline to be determined where center leads exit plastic body.
- 6. "N" is the number of terminal positions.

© Copyright Intersil Americas LLC 2002. All Rights Reserved. All trademarks and registered trademarks are the property of their respective owners.

For additional products, see www.intersil.com/en/products.html

Intersil products are manufactured, assembled and tested utilizing ISO9001 quality systems as noted in the quality certifications found at www.intersil.com/en/support/qualandreliability.html

Intersil products are sold by description only. Intersil may modify the circuit design and/or specifications of products at any time without notice, provided that such modification does not, in Intersil's sole judgment, affect the form, fit or function of the product. Accordingly, the reader is cautioned to verify that datasheets are current before placing orders. Information furnished by Intersil is believed to be accurate and reliable. However, no responsibility is assumed by Intersil or its subsidiaries for its use; nor for any infringements of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Intersil or its subsidiaries.

For information regarding Intersil Corporation and its products, see www.intersil.com

FN2803 Rev 4.00 November 1999

